

## KISM 2025 BUSAN

Re:Innovation of Semiconductor Manufacturing for AI Ecosystem

[WeC1] Advanced Metrology & Inspection, Process Diagnostics & Control, and Yield	
Management III	
Session Date	November 12 (Wed.), 2025
Session Time	09:00-10:30
Session Room	Room C (Grand Ballroom 3, 2F)

[WeC1-1] [Invited] 09:00-09:30

## **Next-Generation Optical Metrology for Advanced Semiconductor Packaging**

Joonho You and Jaeyoung Jang (Nexensor Inc., Korea)

[WeC1-2] [Invited] 09:30-09:50

## Wafer Fracture Stress Due to Edge Cracks and Crack Inspection Method

Hyun-Jung Kim and Ju-Won Lee (Nexus1 Co., Ltd., Korea)

[WeC1-3] [Invited] 09:50-10:10

Development of Designing Motion Profile with Advanced Jerk for Vibration Suppression and High Wafer Throughput

Heejae Byun, Kyobong Kim, Jaewon Choi, Sangoh Kim, and Janghwan Kim (SEMES, Korea)

[WeC1-4] [Invited] 10:10-10:30

Al-Enhanced Metrology Integration Framework for Atomic Layer Deposition Systems
Jihye Seo (KETI, Korea)